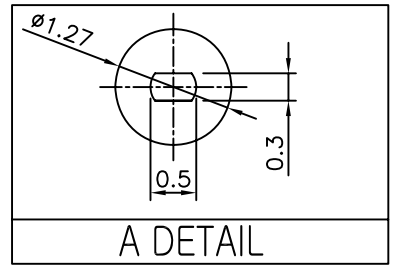
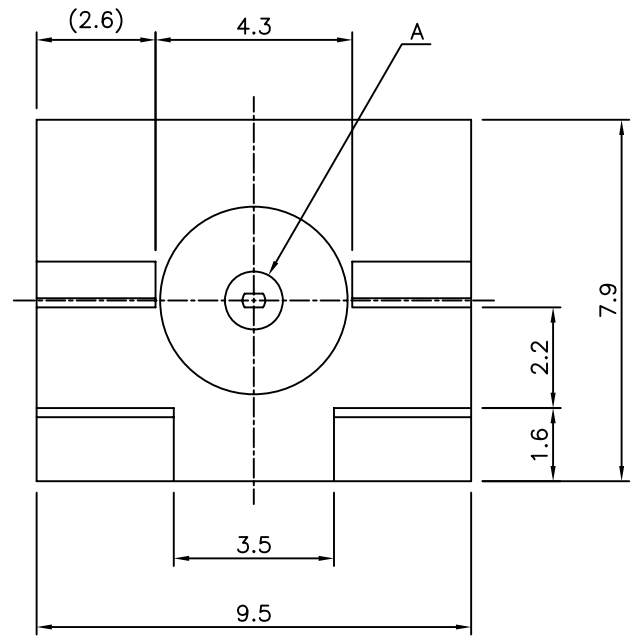
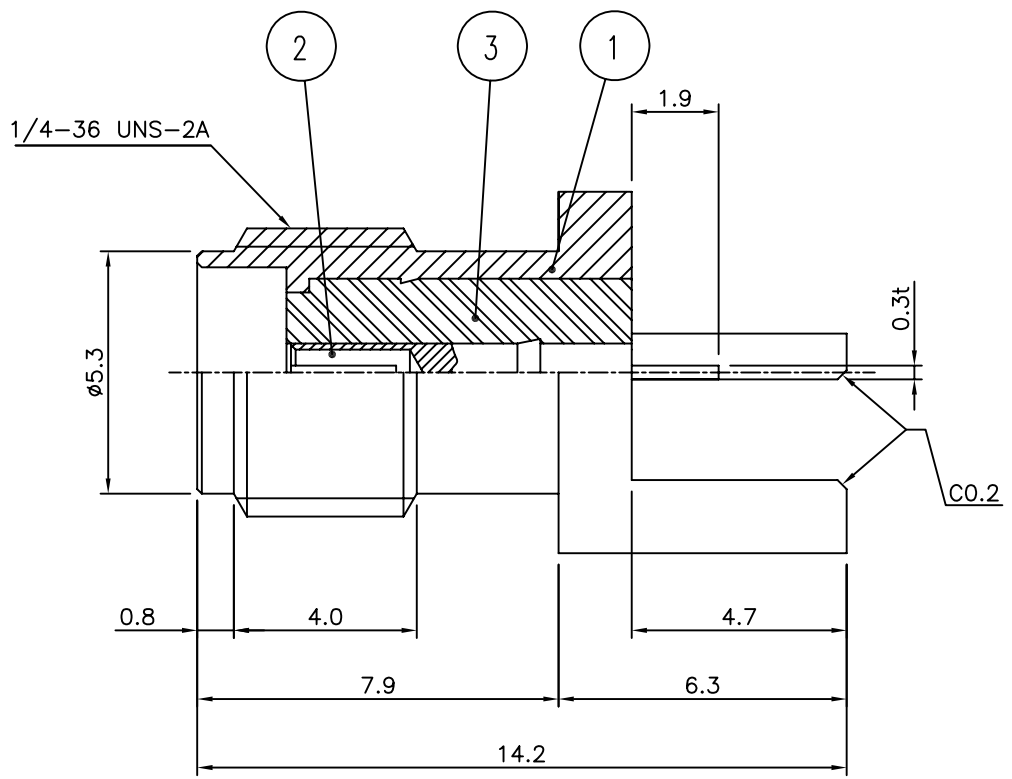


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2015.07.30.



주기
 1.CEQ00069-N/1 JIG를 이용하여 PIN 0.3t
 부위 부러짐 주의하여 조립하고 개별 포장 할 것

3	INSULATOR	1	TEFLON		DIN01076-N/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT01636-5/1
1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD03990-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2015. 07. 30.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY	S.M.LEE	TITLE SMA50 PCB JS-4R (Edge)
		DRAWN BY	H.J.LEE	
FINISH		SCALE	6/1	DWG NO. CN03462-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	

A4

